



phoenix|x-ray

ovhm technology

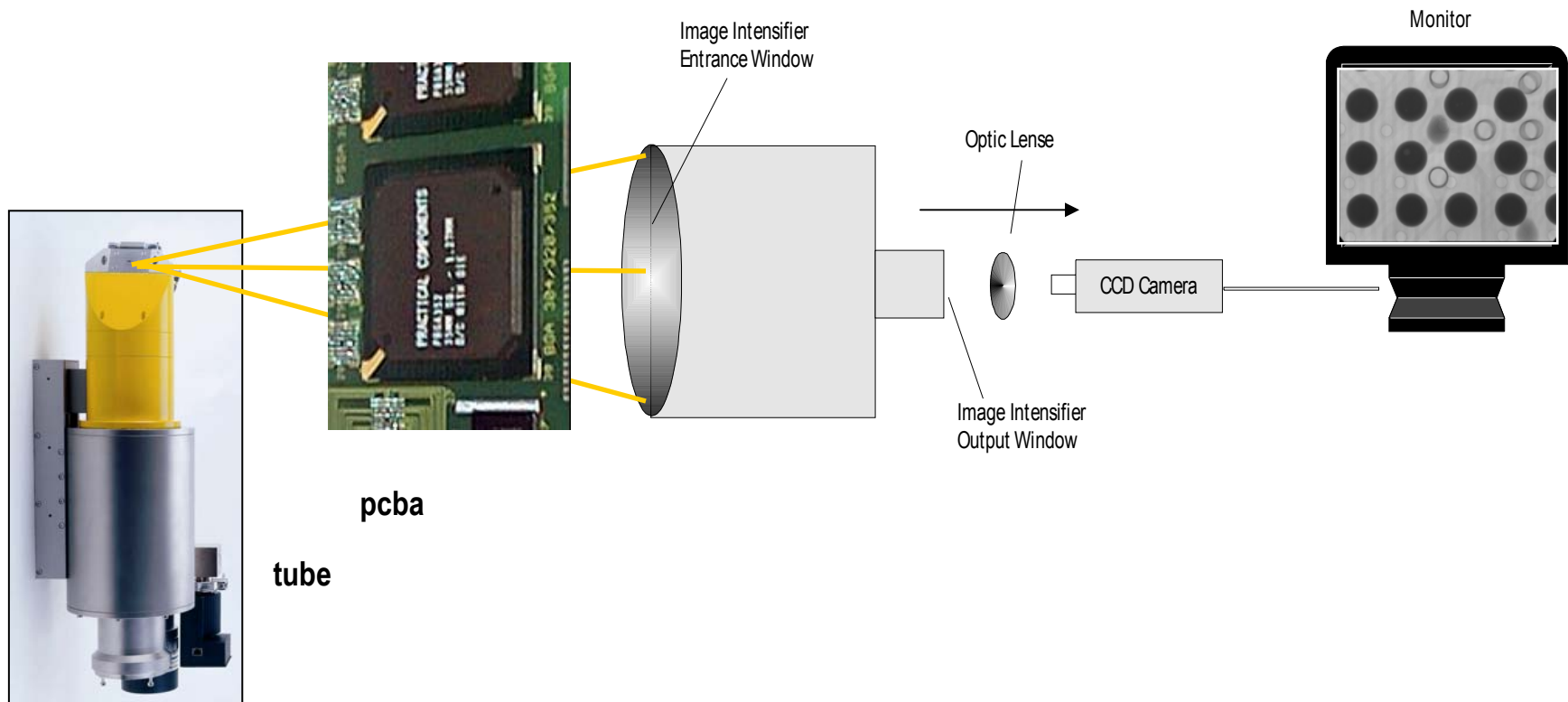
- ▶ **Standard X-ray inspection**
- ▶ **ovhm technology**
- ▶ **Applications**
- ▶ **automatic wetting inspection**
- ▶ **Summary**

Bob Mazuik

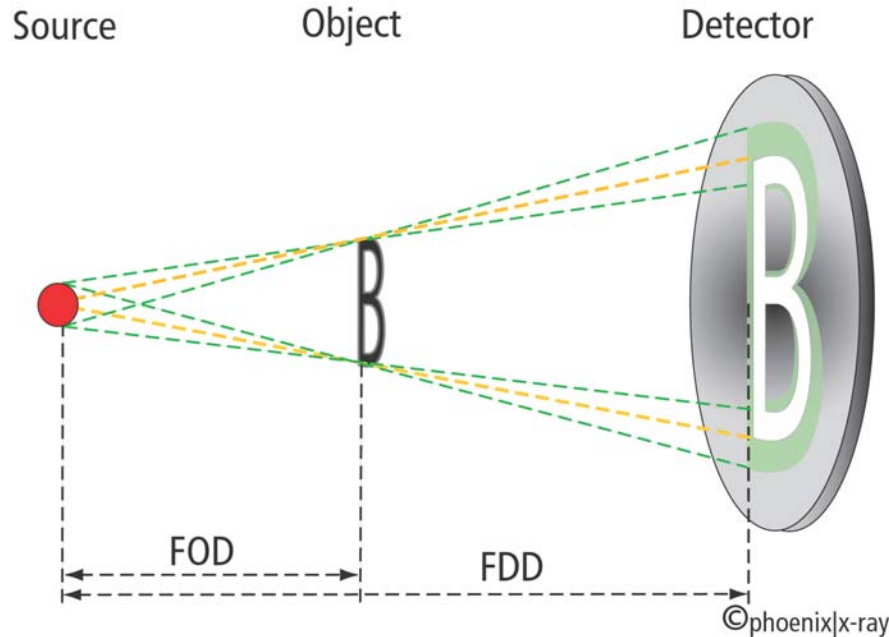
Standard 2D X-ray inspection

The X-ray image results from:

- Different absorption coefficients of elements (solder, moulding, etc.)
- Absorption changes with the material thickness



Fundamentals of X-ray technology



- ▶ Geometrical magnification = FDD / FOD
- ▶ Lateral resolution (at large magnification) = source size
- ▶ Contrast depends mainly on the detector

V.E. Cosslett

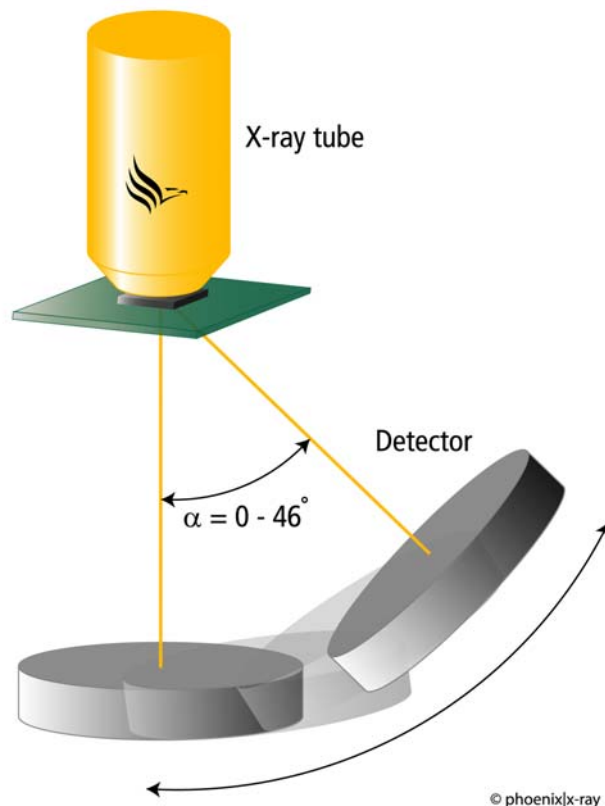
W.C. Nixon

Cambridge 1951

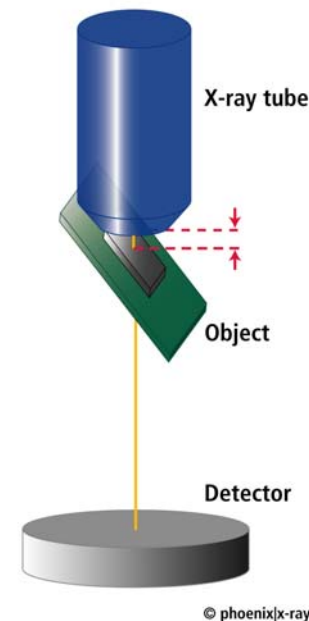
*“X-ray Shadow
Microscope”*

*Nature 10 (1951)
pp.24*

ovhm|module



► The sample needs not to be tilted using the ovhm technique. Hence, there is no loss of magnification due to longer focus-object distance.



Advantages

no loss of magnification in oblique view



higher defect detectability

no object tilting (isocentric mode)



easier manipulation

realistic image

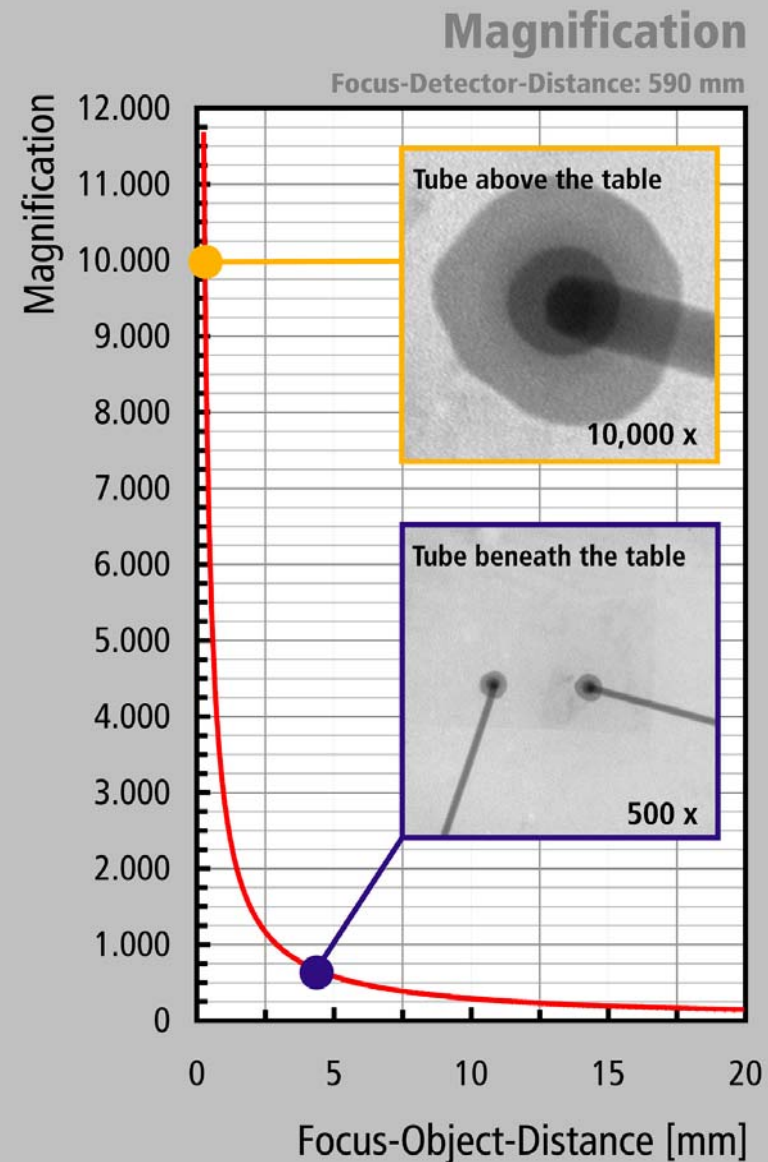


easy interpretation

Magnification Advantage

The magnification increases with a smaller Focus-Object Distance.

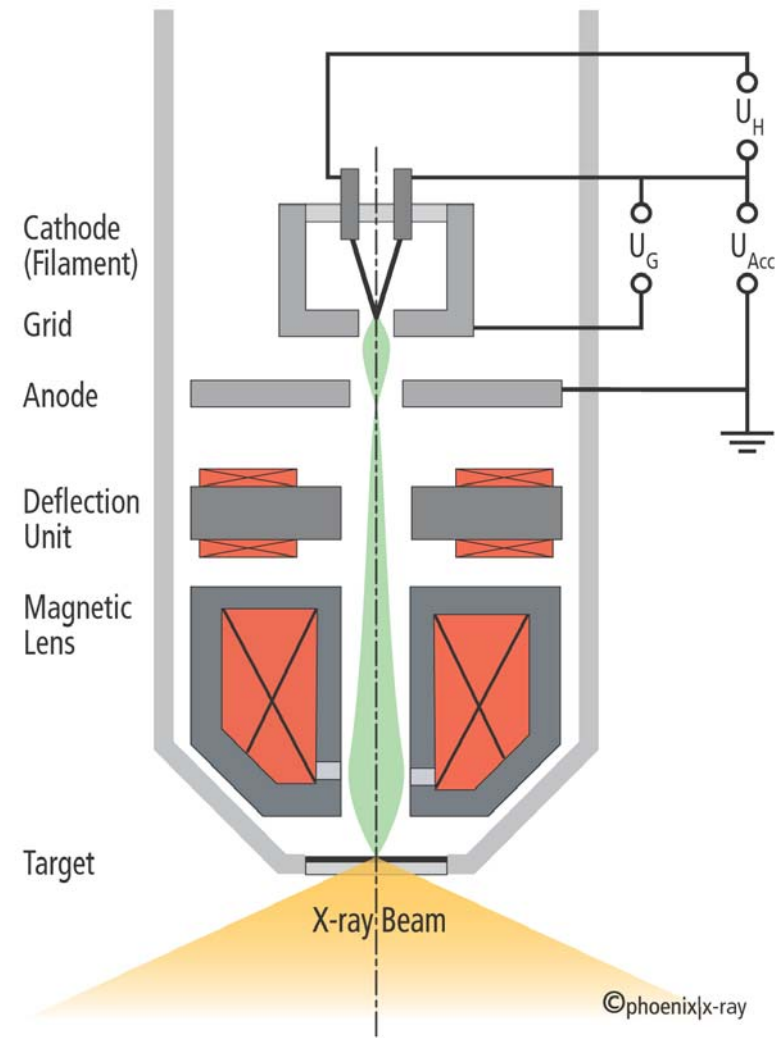
Small Focus-Object Distance changes result in large magnification differences.



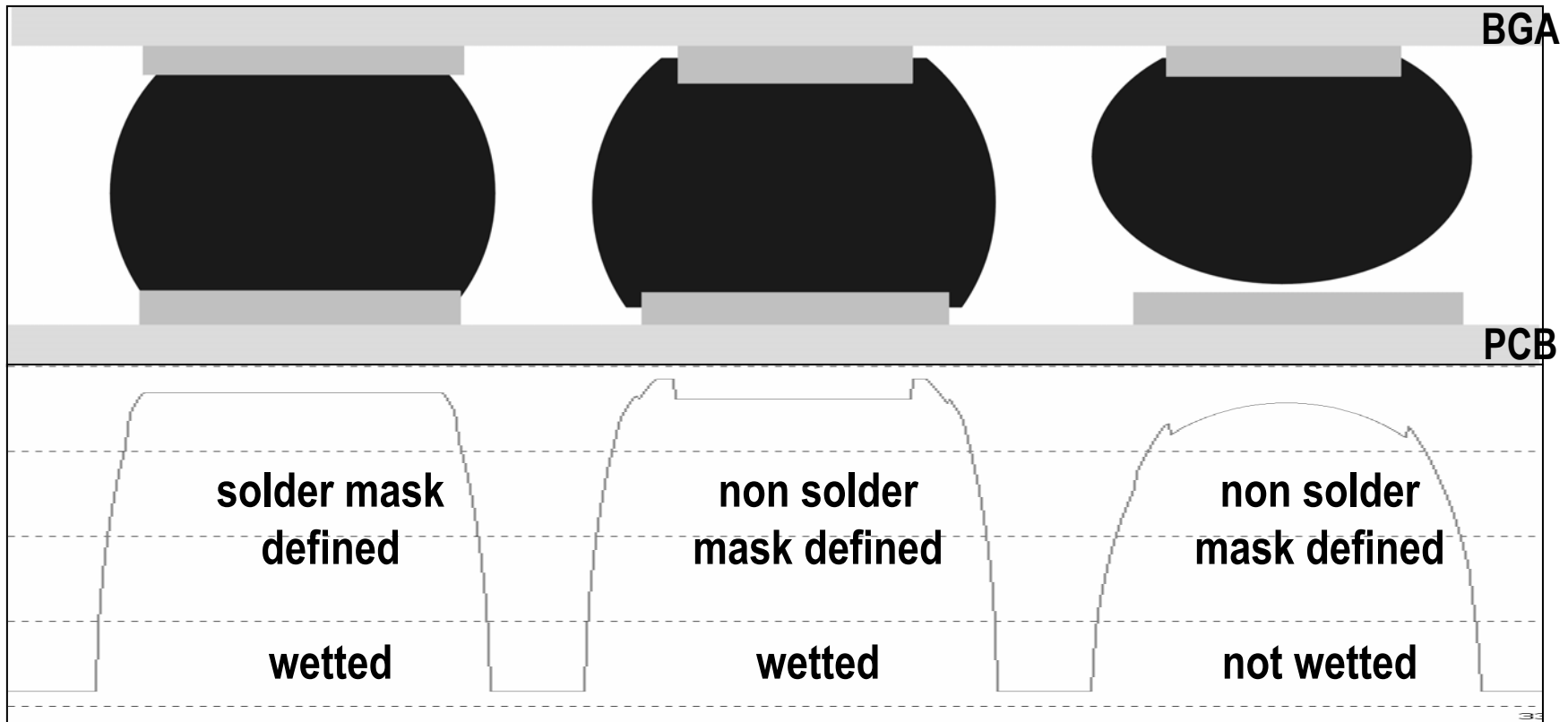
X-ray tubes

Beam angle must be higher as to achieve the ovhm angle (in general 170°)

For high magnification the tube must be mounted on the top of the X-ray system in order to get as close as possible to the component

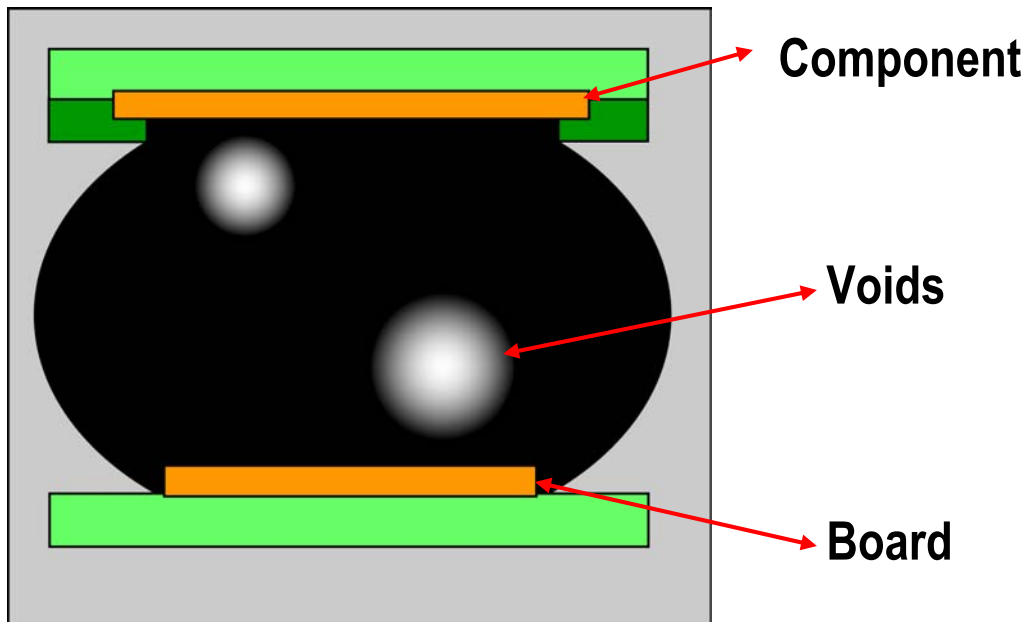


Grey value distributions for different pad configurations



BGA, CSP and FlipChip solder joints

Typical set-up



Analysis Tasks

Integrity of
board and component
interconnection

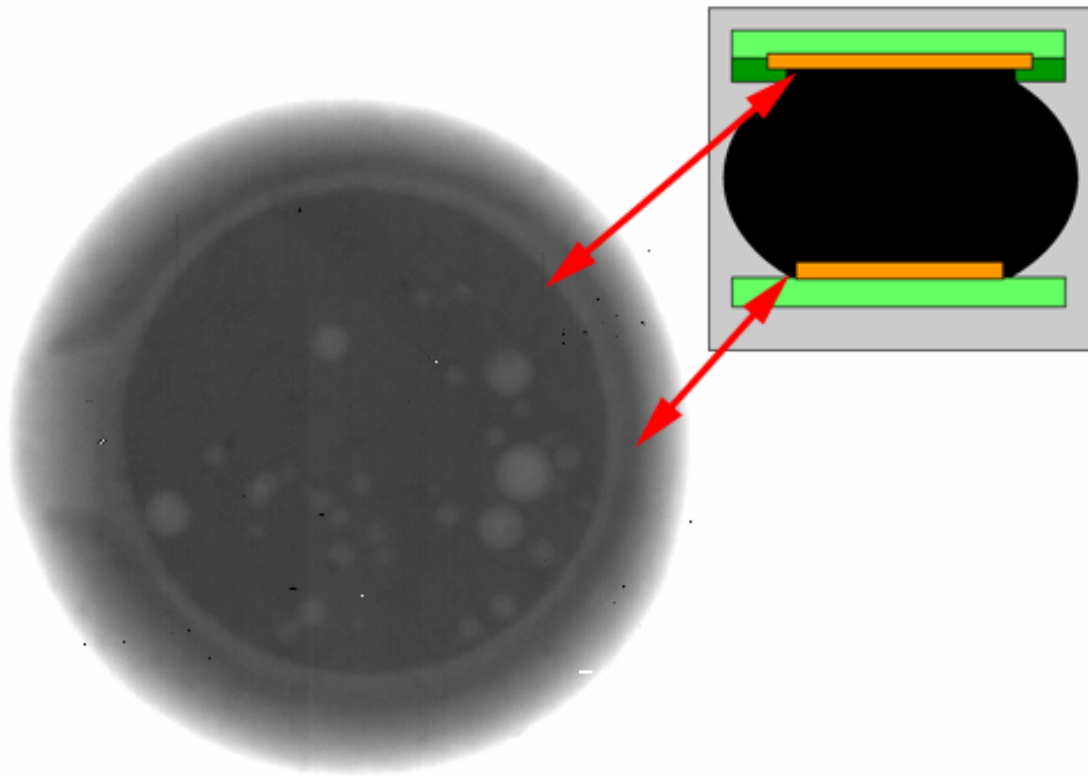
Determination of void
position

Ball Shape

Detection of
opens

BGA, CSP and FlipChip solder joints

analysis in top-down view



Problem

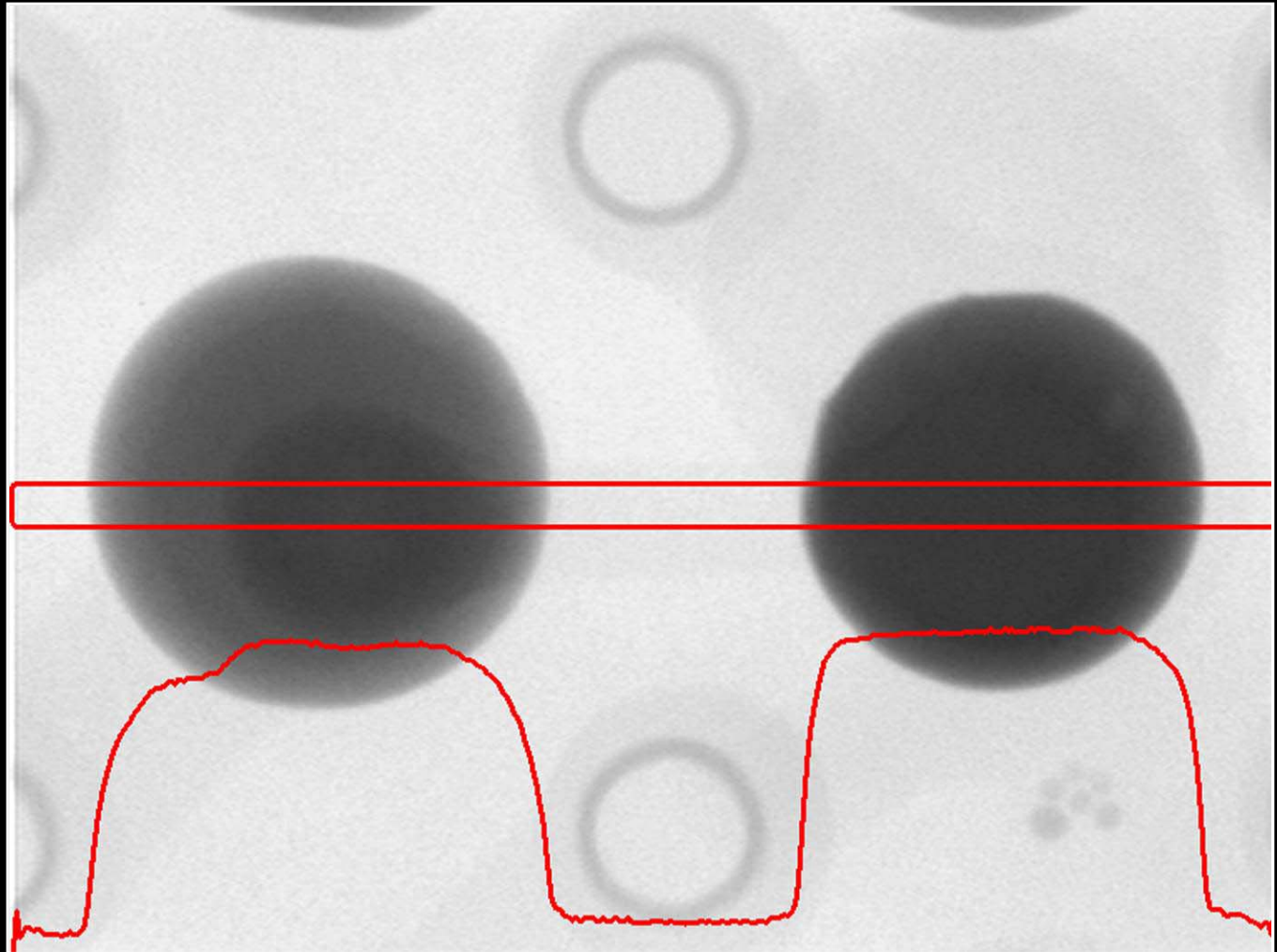
Overlap of object
features in top-down
images



interpretation
of images
requires additional
information

**BGA
solder joints**

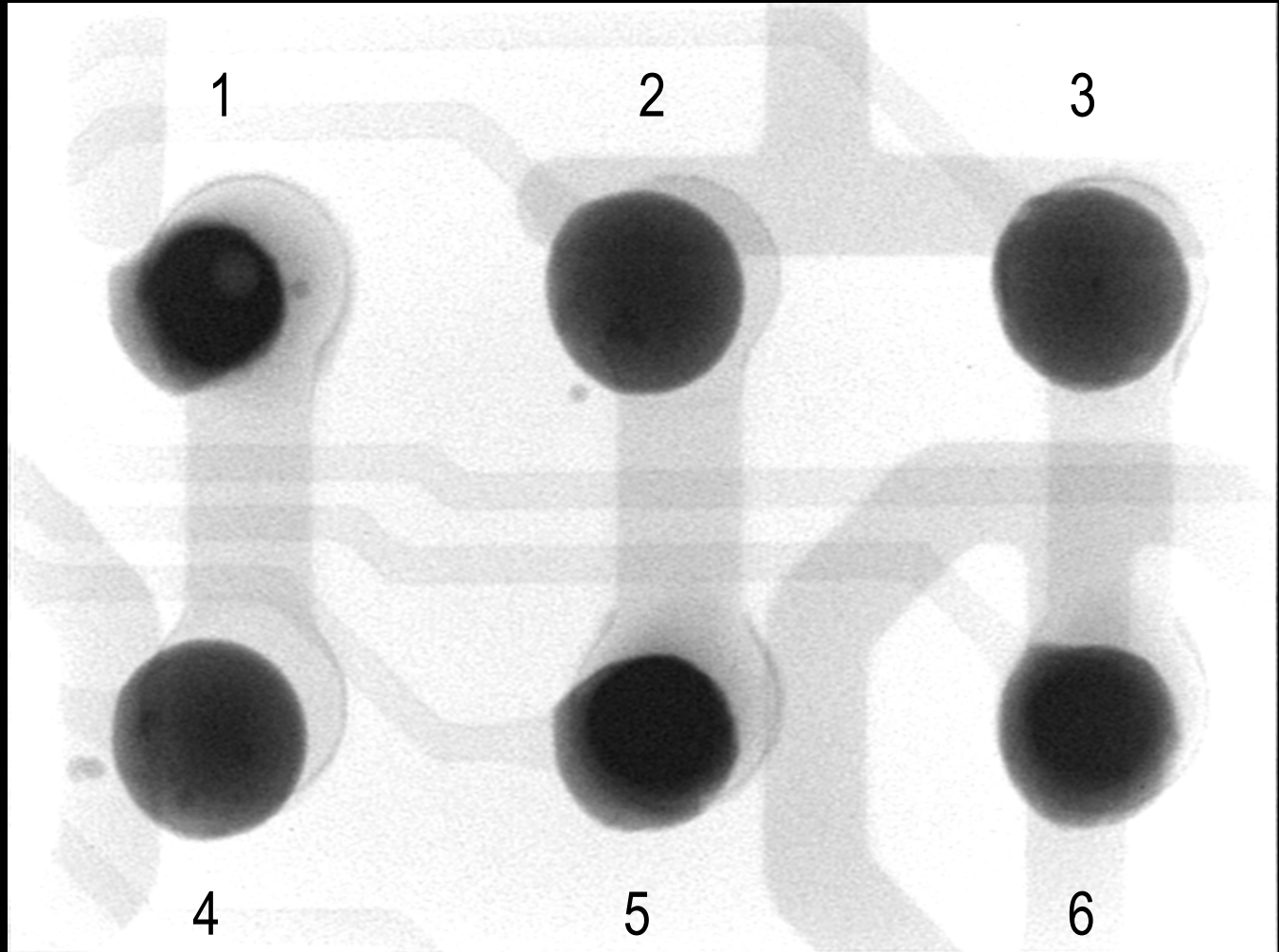
**Gray level
plot**



- ▶ Identification of open balls with gray level analysis
- ▶ **Disadvantage:** Not always clear

**μBGA
solder joints**

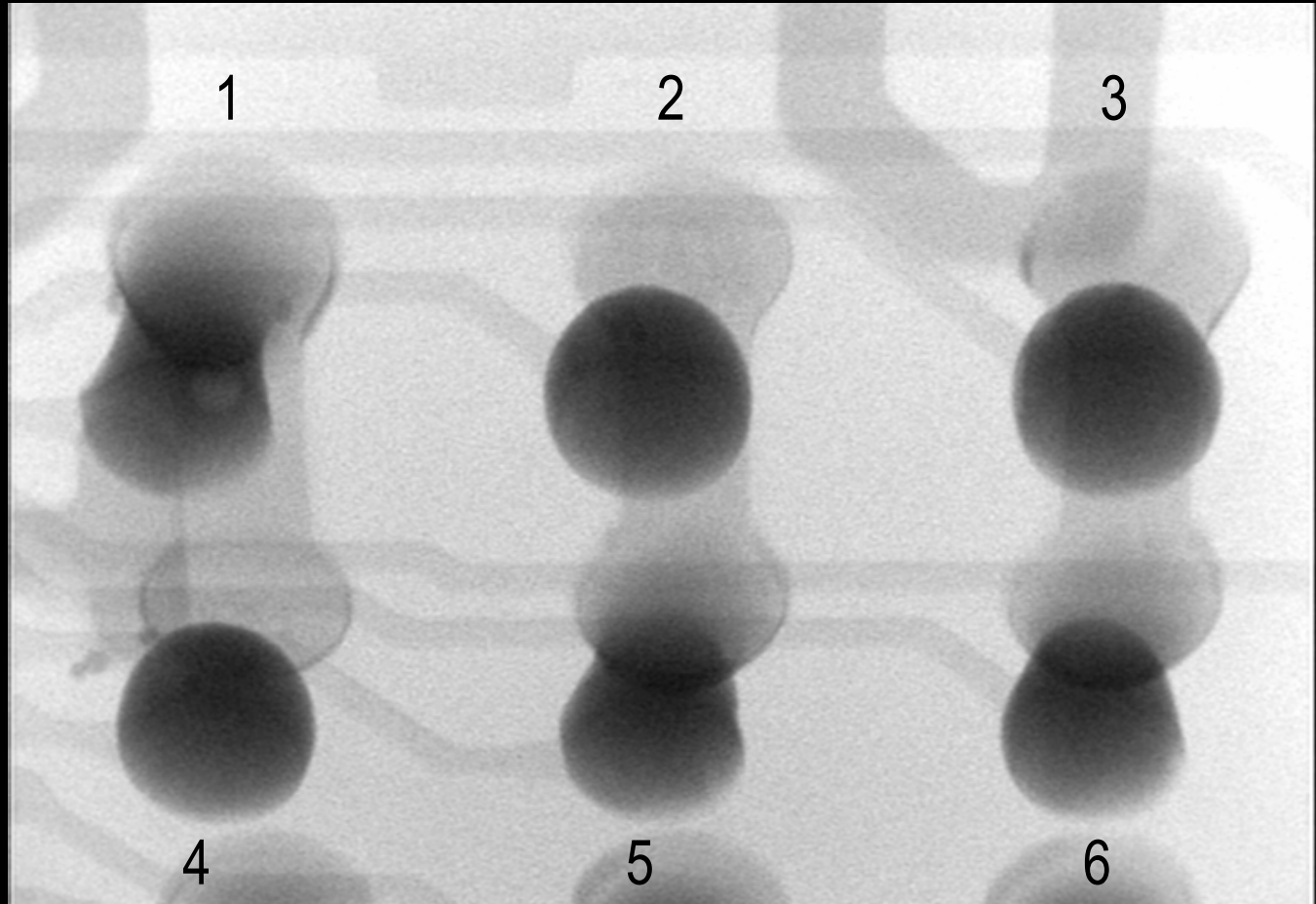
**top down
view**



- ▶ Three solder joints (No. 2,3,4) are not wetting to the board pads
- ▶ One void is visible (No.1)

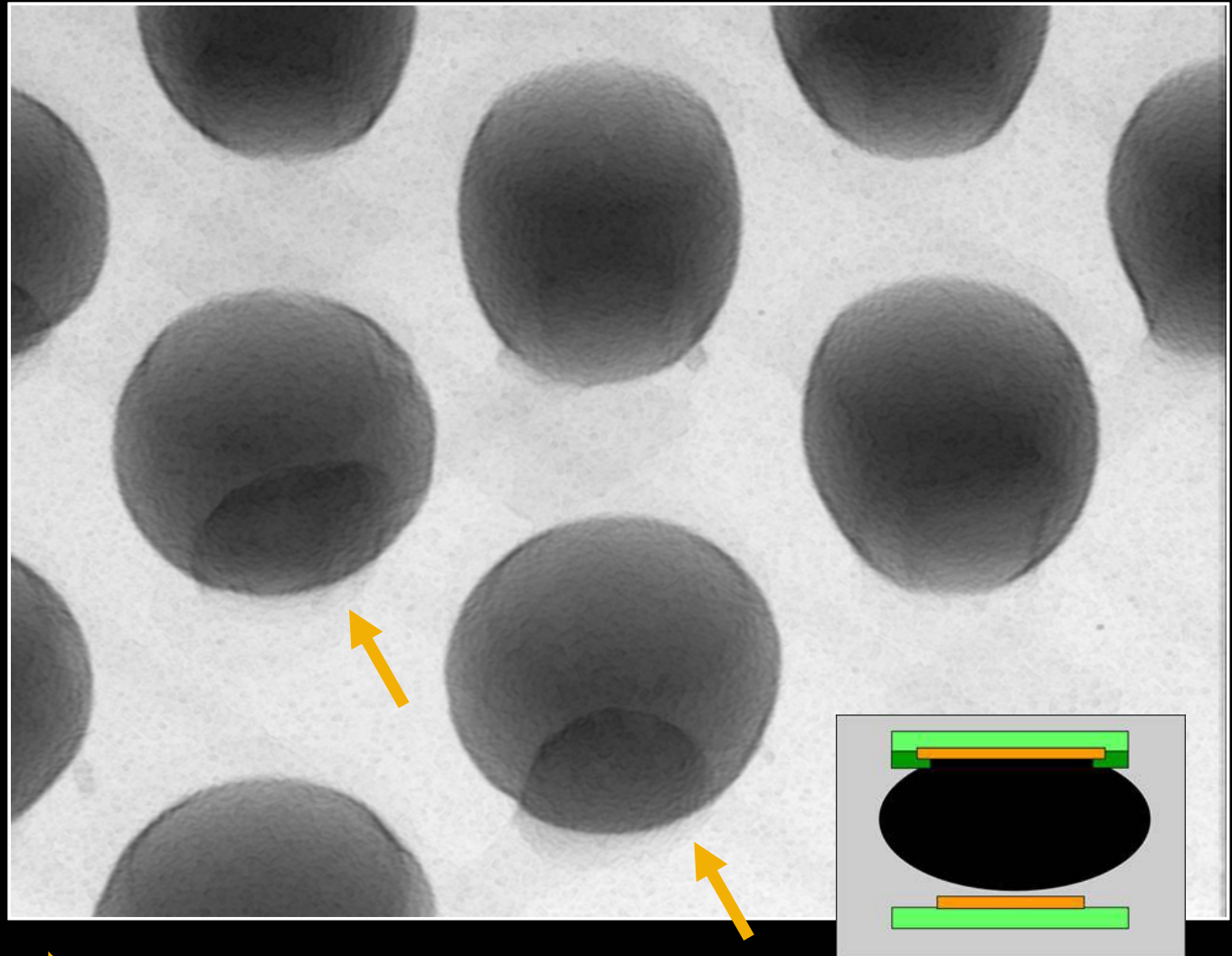
**μBGA
solder joints**

ovhm view



- ▶ Three solder joints are clearly open (No. 2,3,4)
- ▶ The void (No.1) is located near the component pad
- ▶ The solder joint above right (No.6) is in contact to the board, but with insufficient wetting (no meniscus)

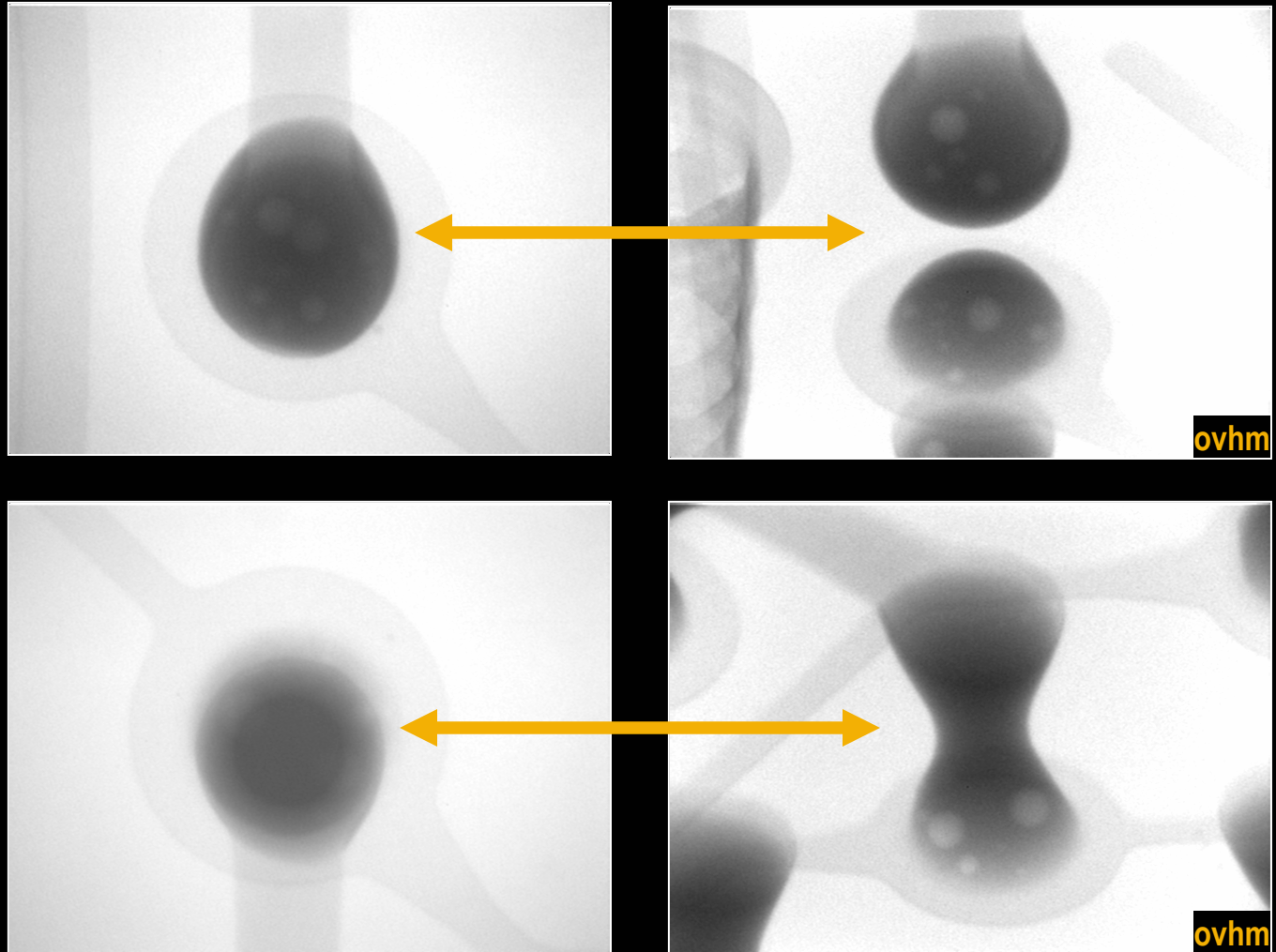
BGA
solder joints
ovhm|module



- ▶ Two pads are not wetted.

CSP solder joints

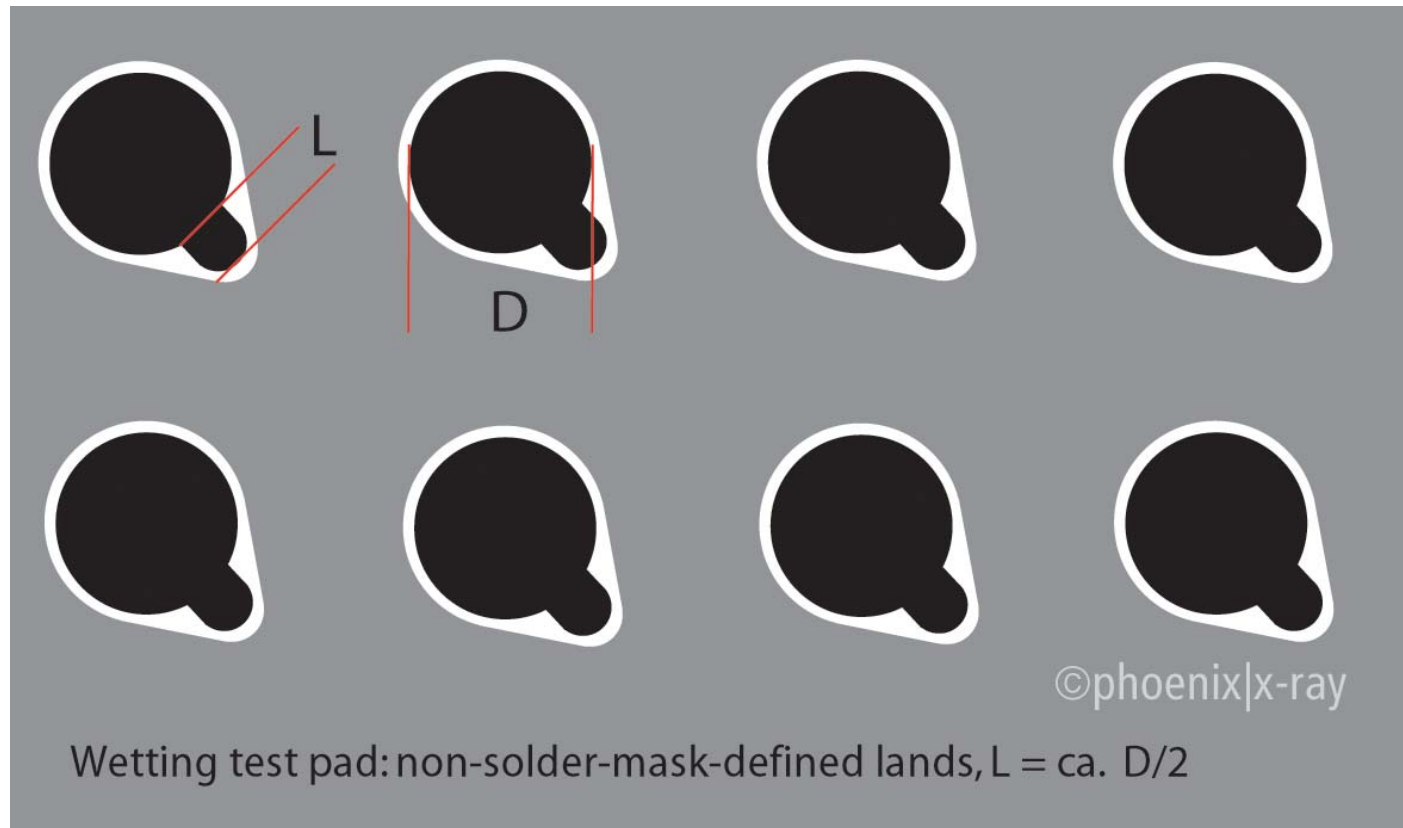
left: topdown
right: ohvm



- ▶ The upper solder joint which looks quite normal in top-down view is shown to be definitely open in the ohvm. The lower one turns out to be just closed but strongly distorted.

Wetting test pads

for automated wetting analysis



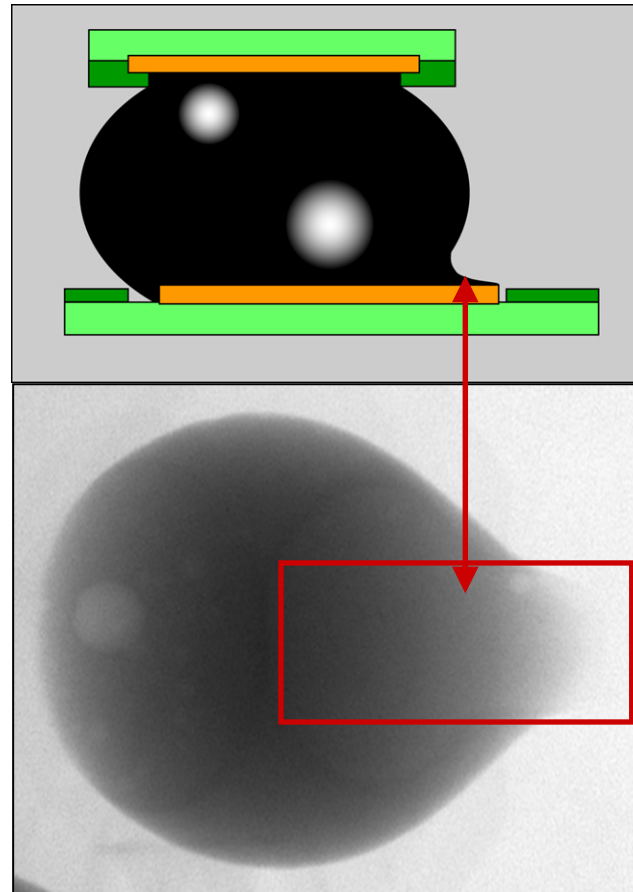
Inspection of the gradient analysis

Advantages:

No influence
of other properties,
therefore it is unique.

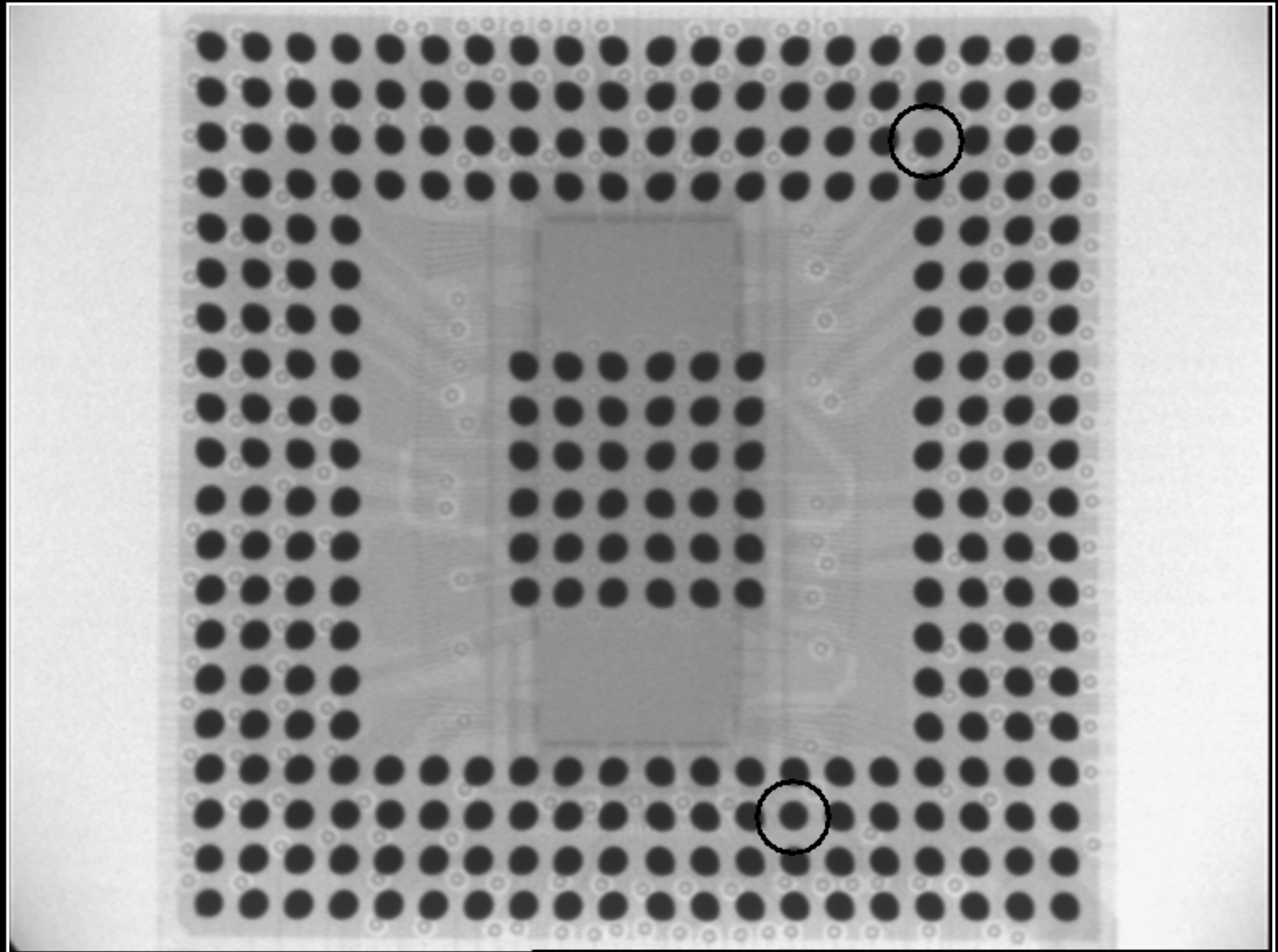
Very sensitive.

Easy to define the
pass/fail values.



BGA solder joints

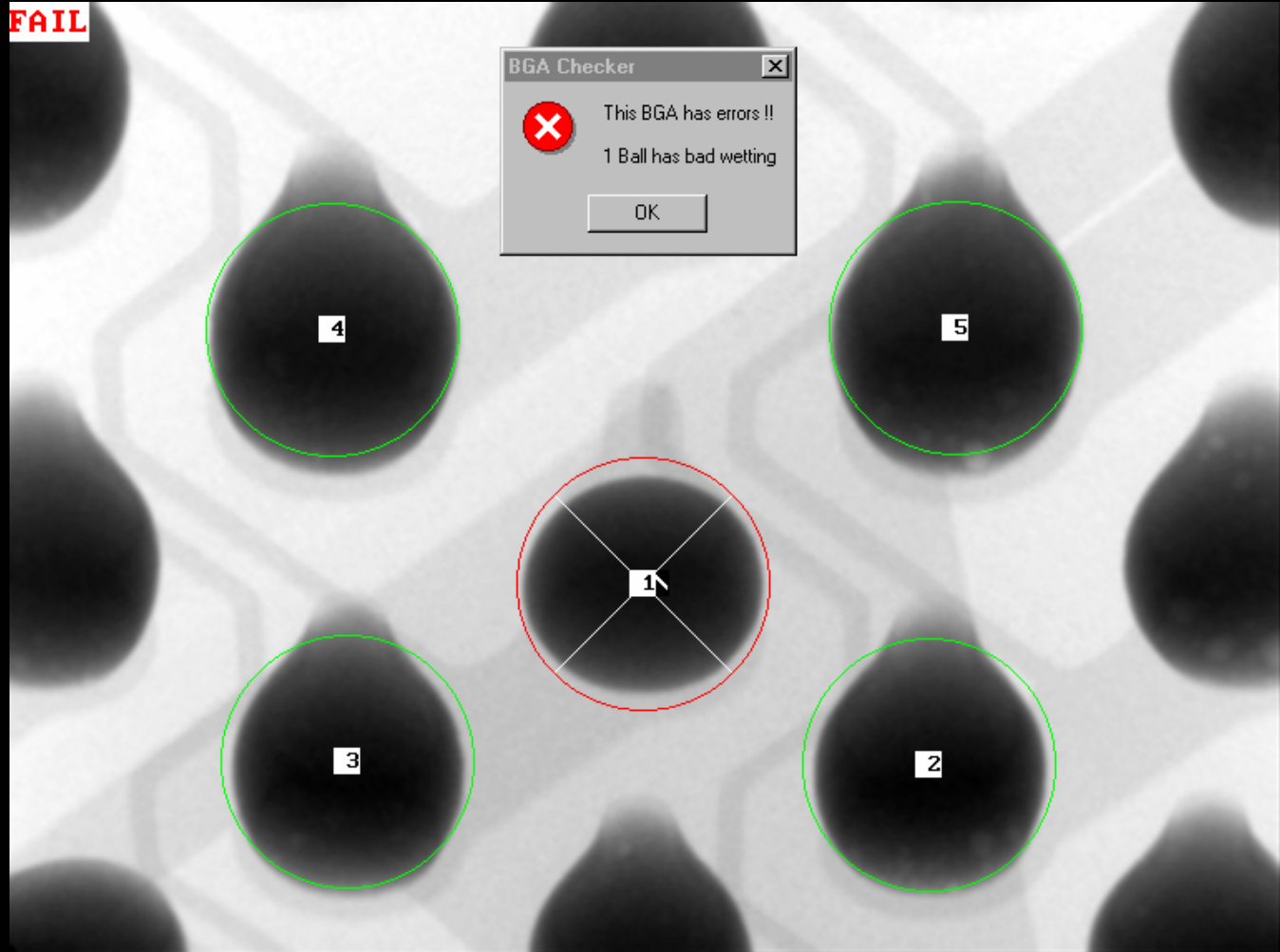
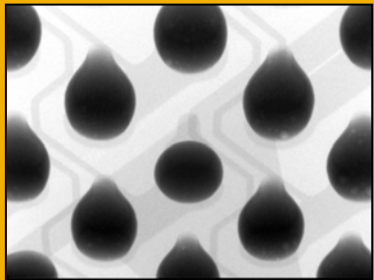
automated wetting analysis



- Overview image of a BGA with wetting test pads (keyholepads). Two wetting defects are present.

BGA solder joints

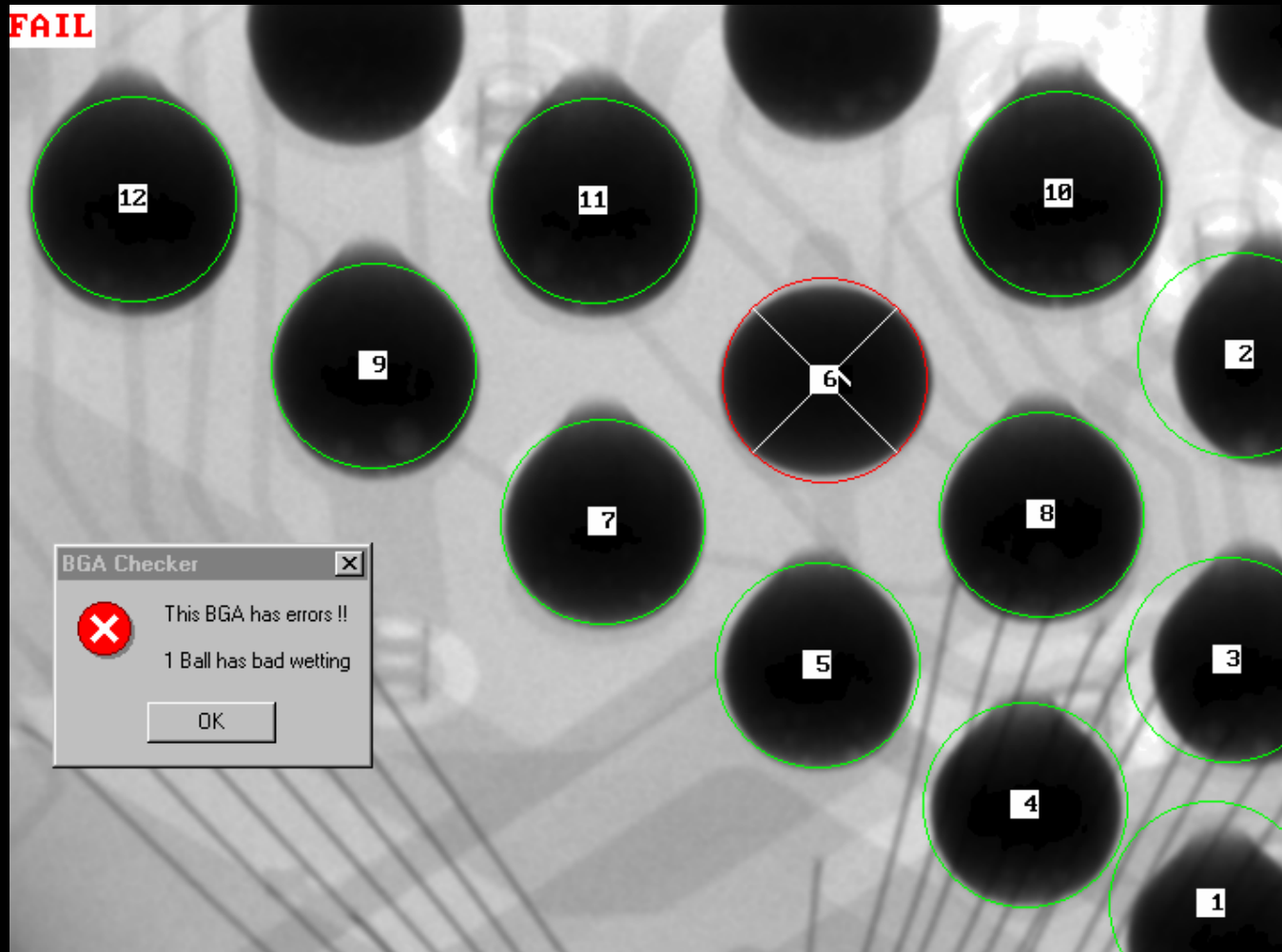
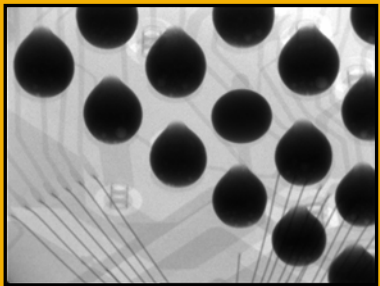
automated
wetting
analysis



- First defect: From the grey level slope (gradient) non-wetting joints can be identified in the ovhm image.

BGA solder joints

automated
wetting
analysis



- ▶ Second defect: From the grey level slope (gradient) non-wetting joints can be identified in the ovhm image.

Summary:

The ovhm technology allows highest oblique view inspection

The ovhm technology gives clear information about the wetting condition

Offline and Inline

Automatic inspection

Unique technology for automatic wetting analysis

Any Question?

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